

FIG.1

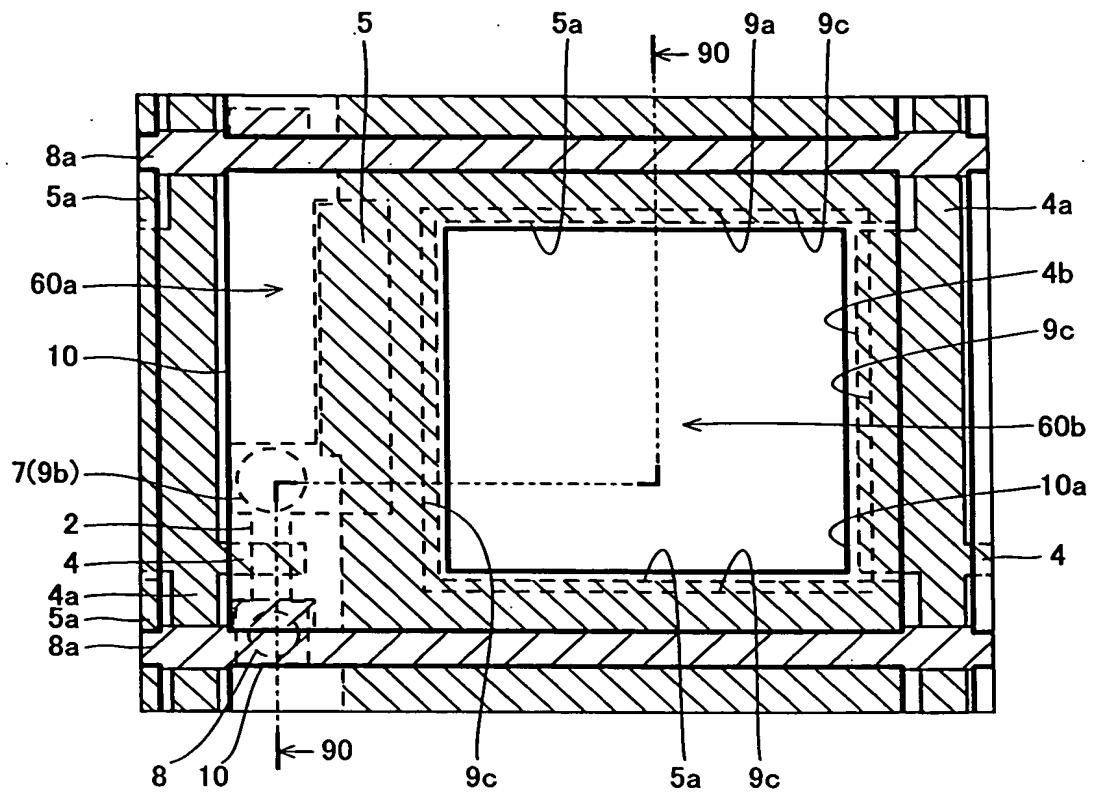


FIG.2

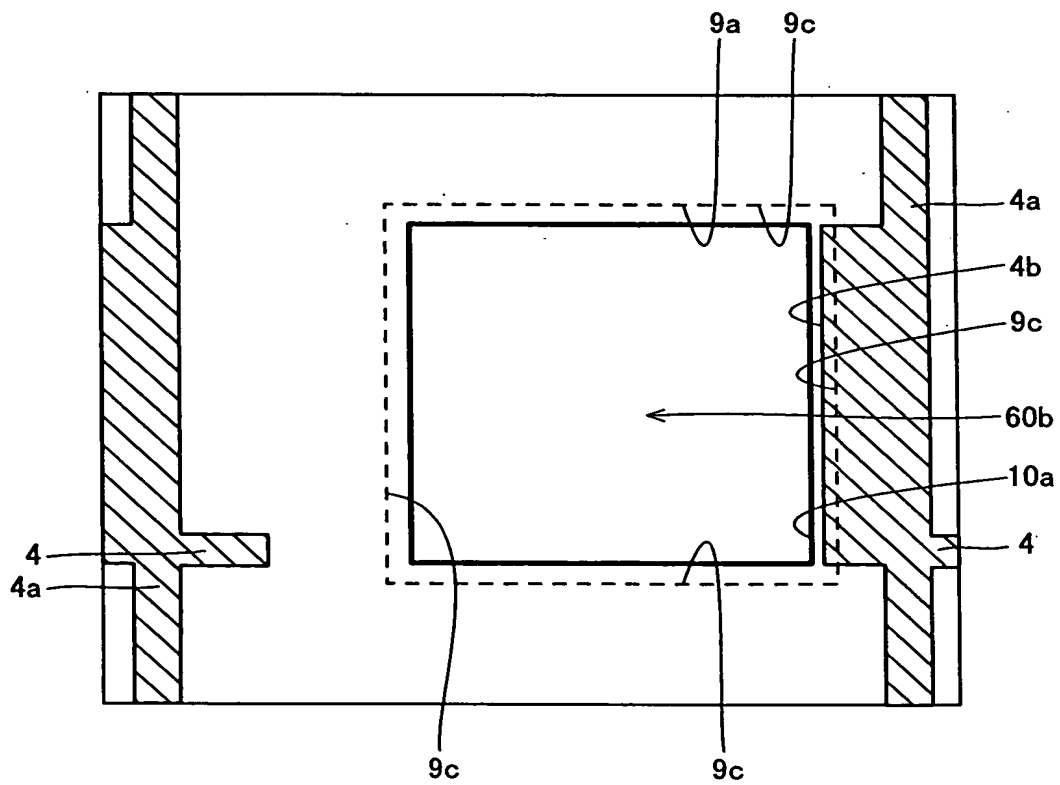


FIG.3

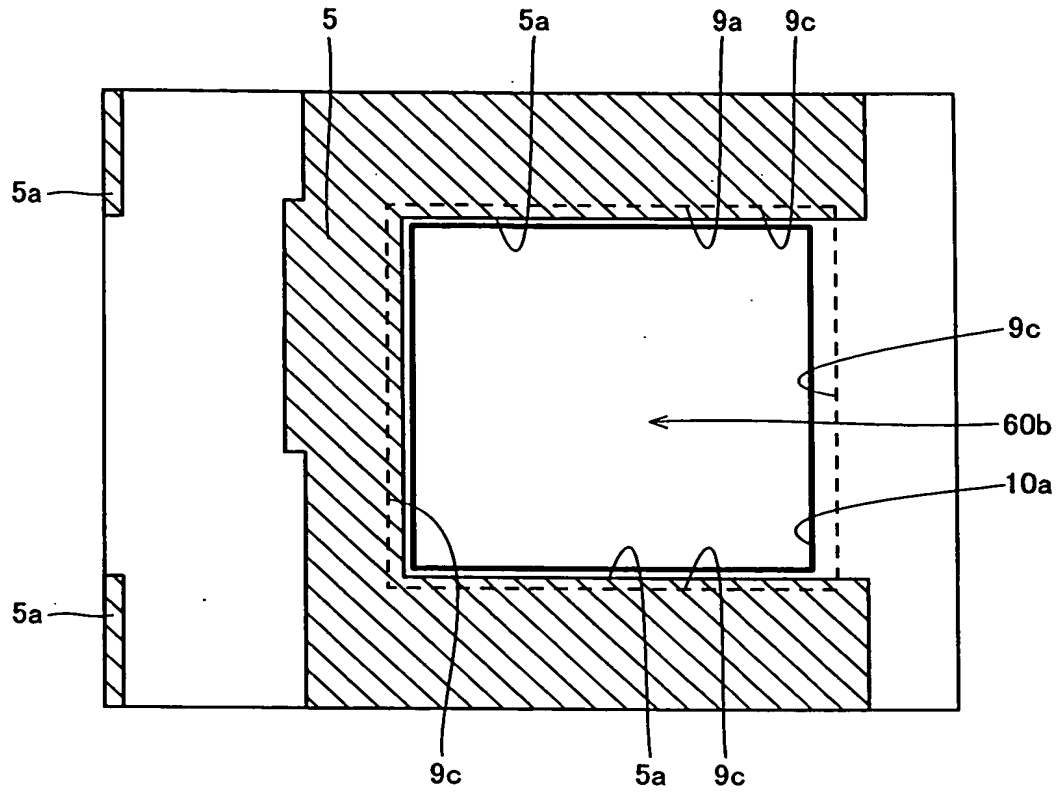


FIG.4

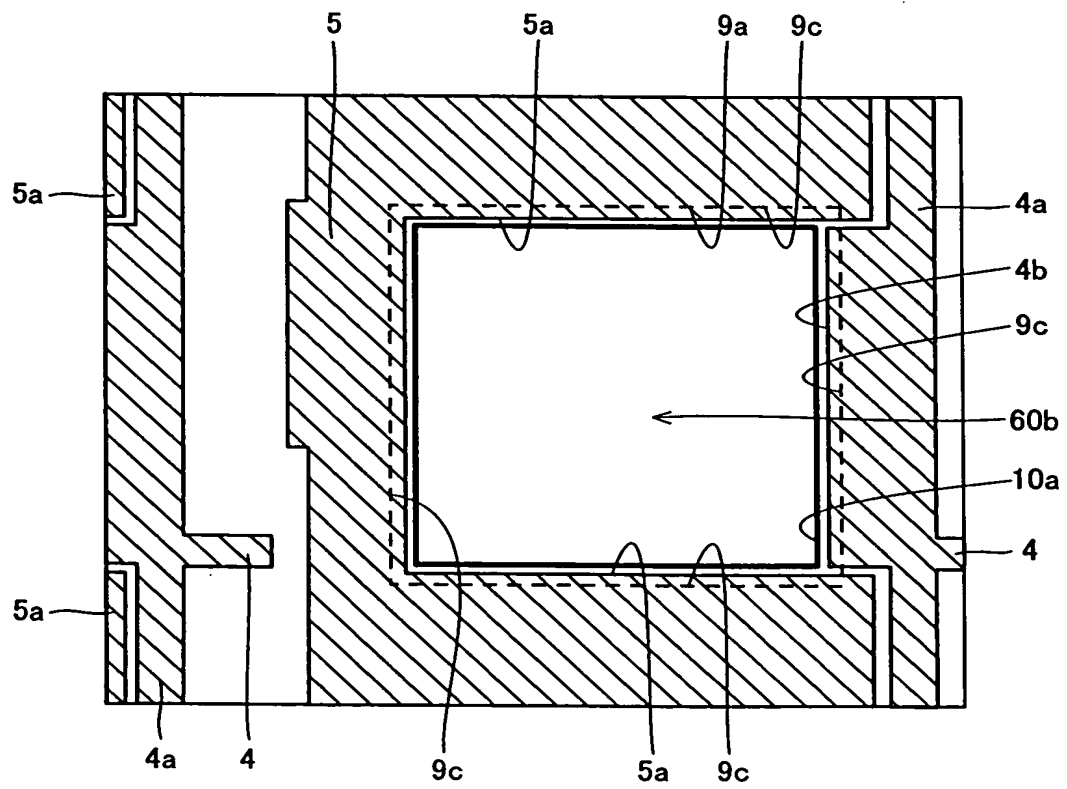


FIG.5

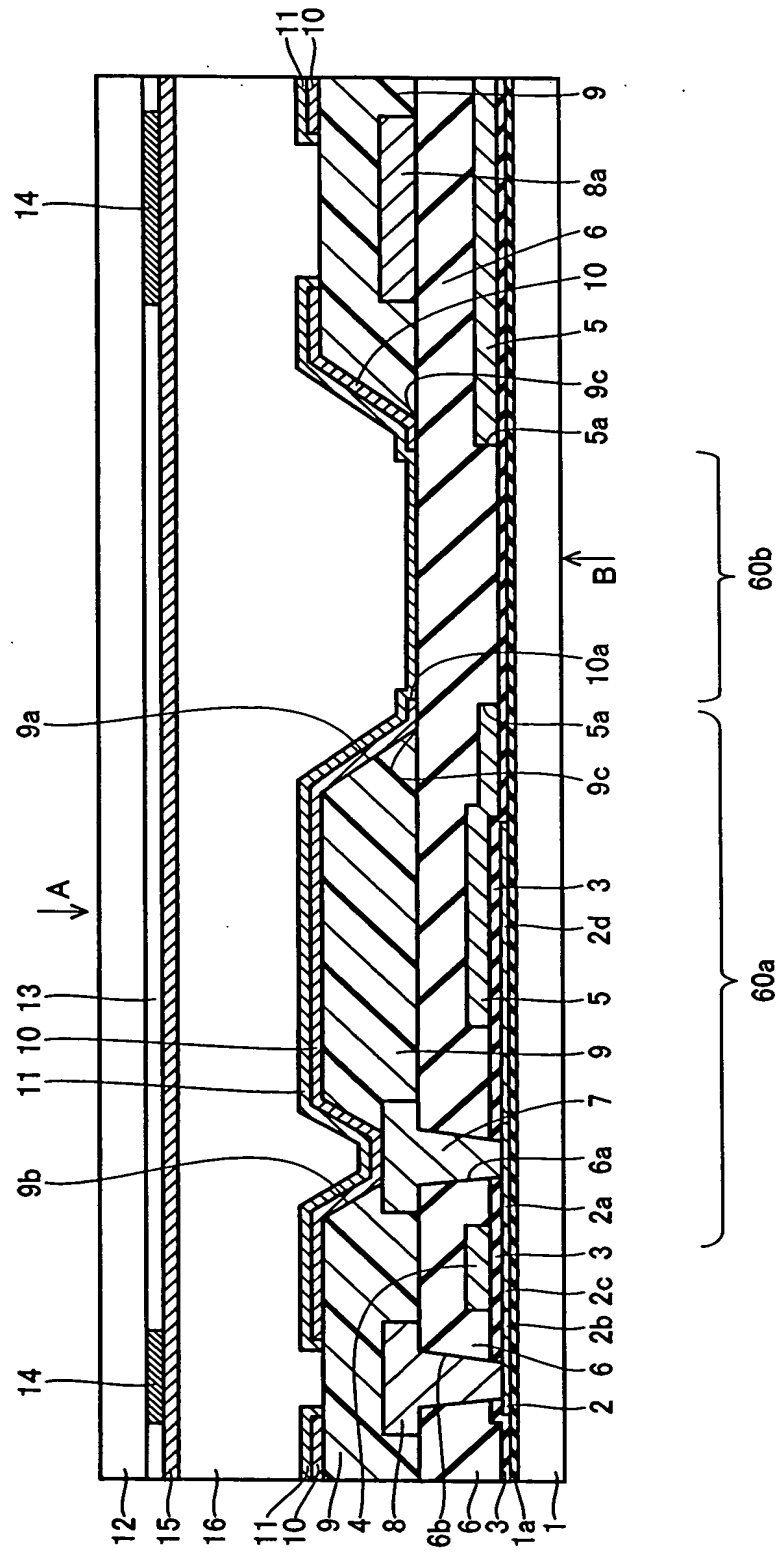
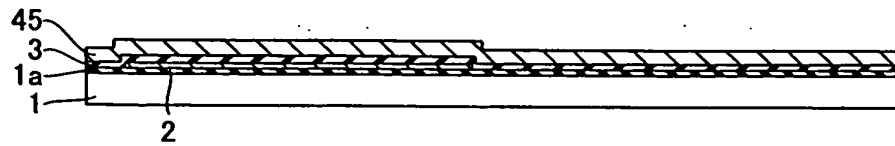
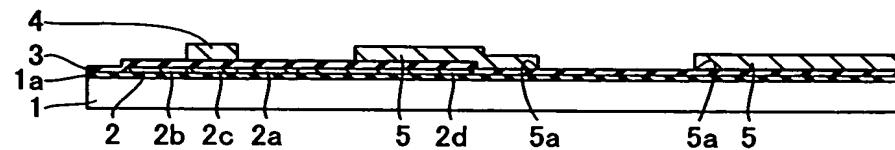


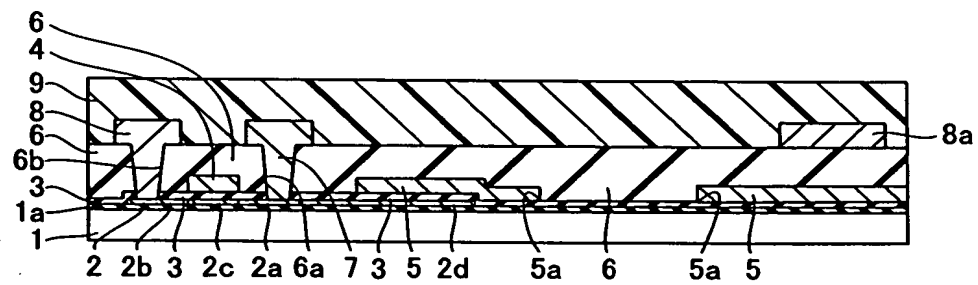
FIG.6



**FIG.7**



**FIG.8**



**FIG.9**

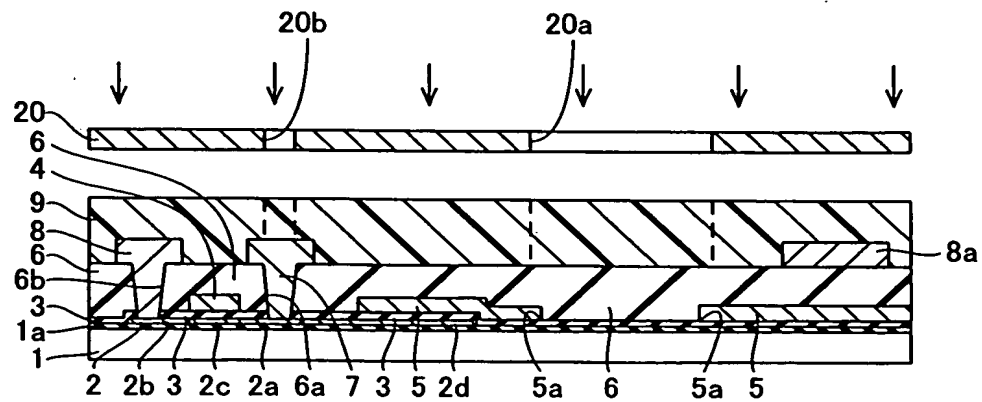


FIG.10

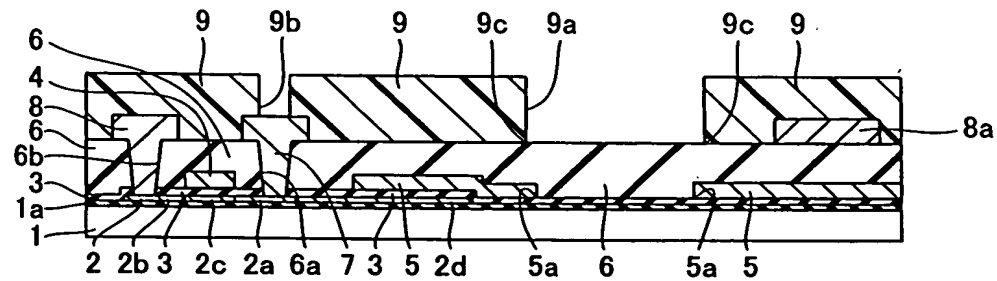


FIG.11

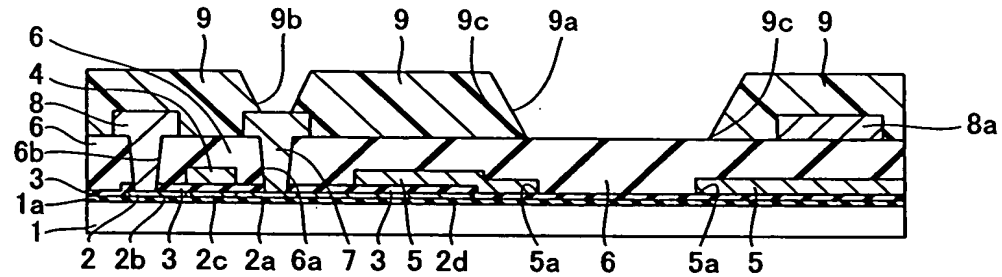


FIG.12

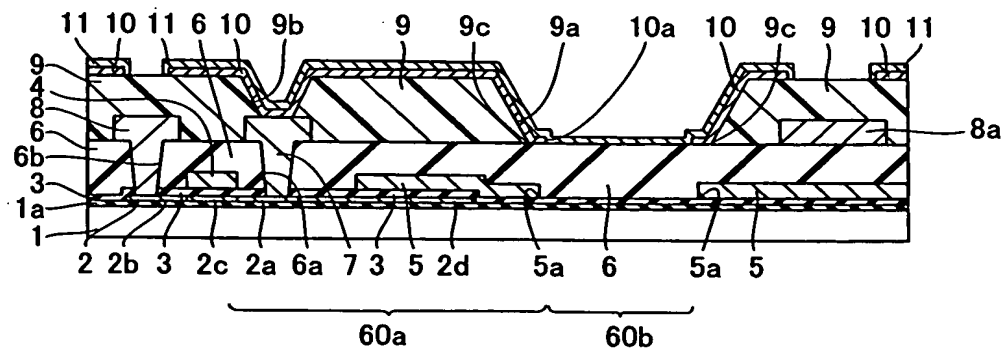
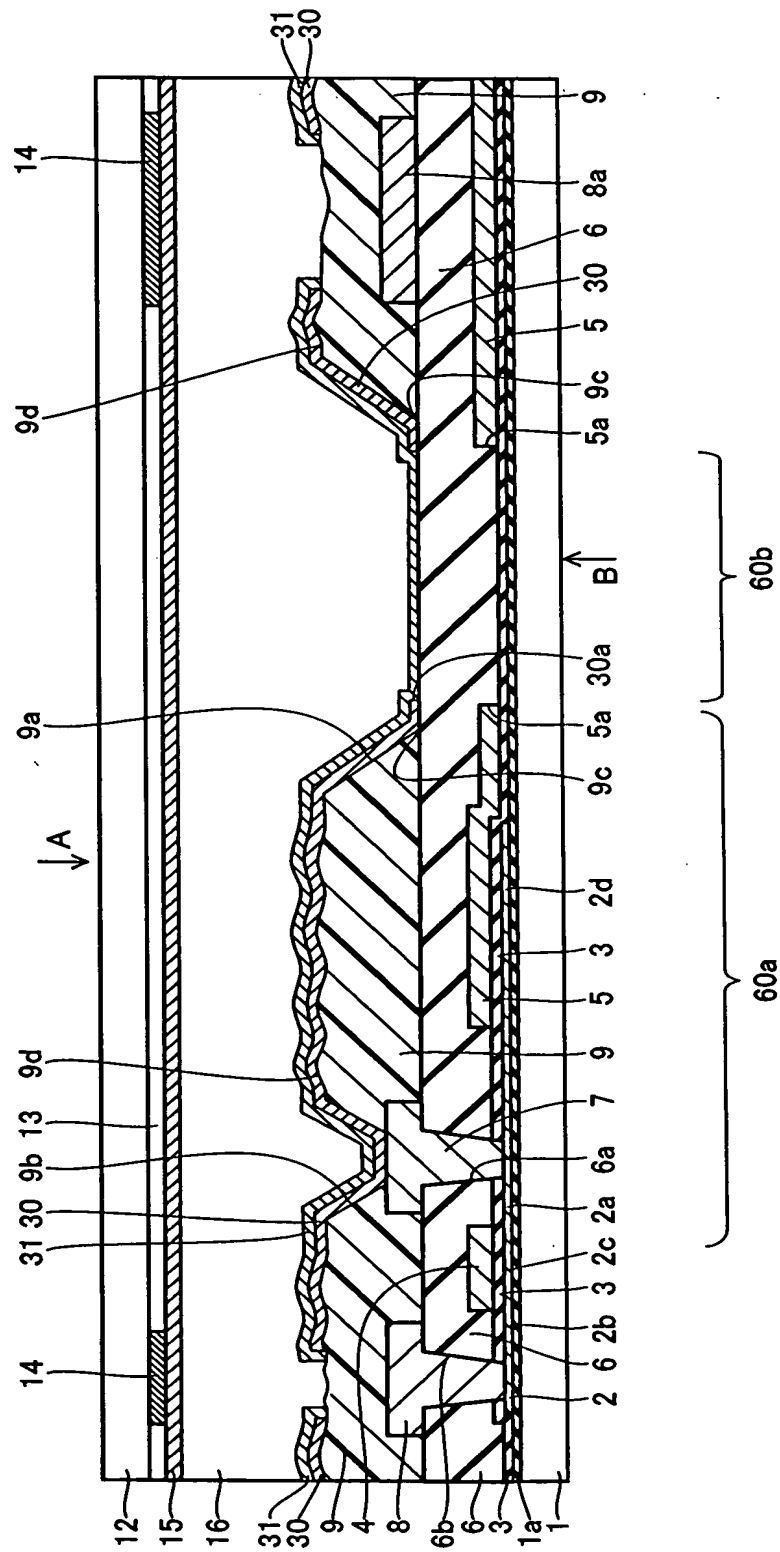
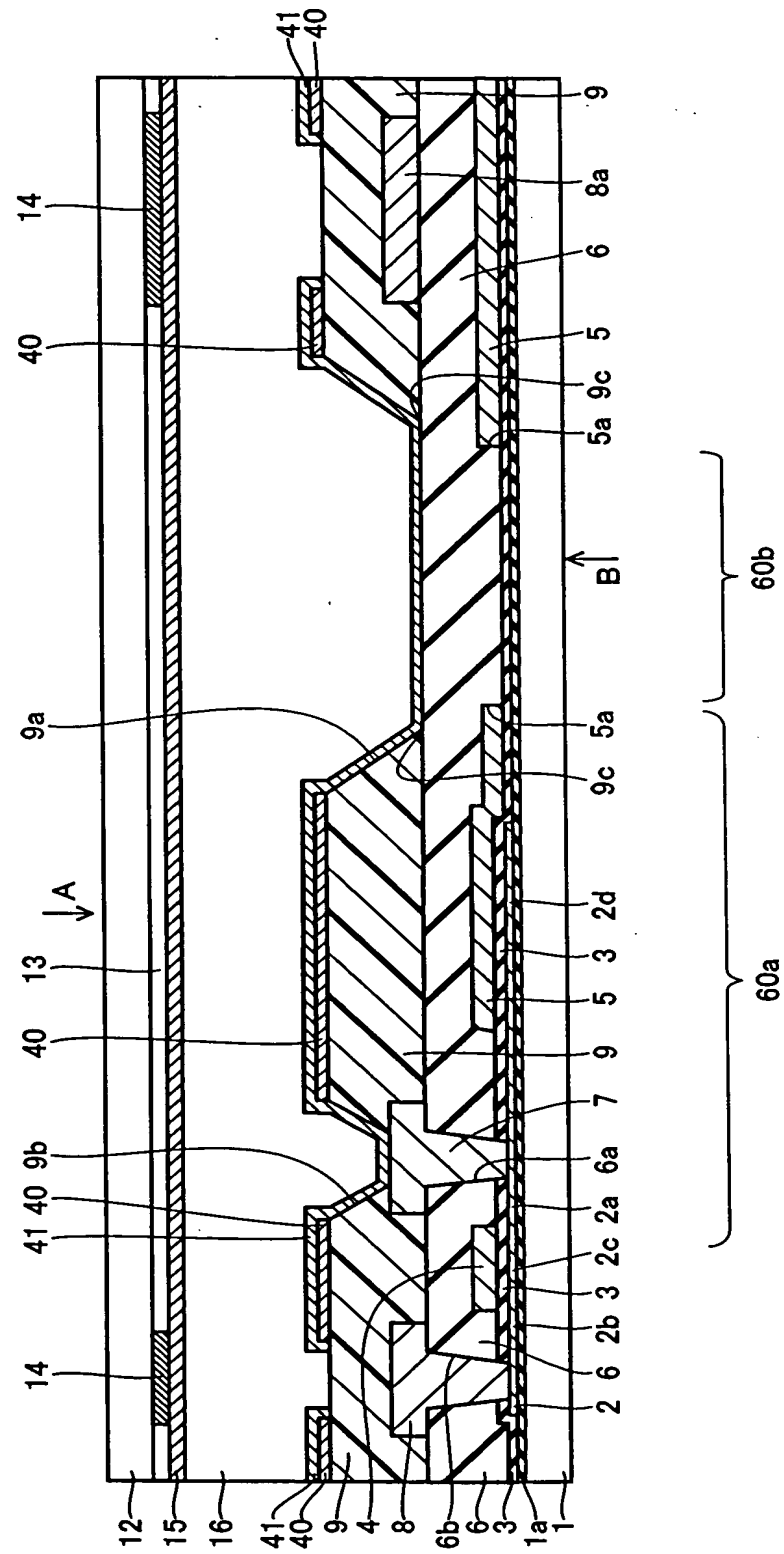


FIG.13



**FIG.14**



This diagram shows a cross-sectional view of a multi-layered electronic device assembly. The assembly consists of several layers and components, labeled with reference numerals:

- 8a**: Top and bottom outermost layers, likely a substrate or protective coating.
- 8**: A central rectangular cavity or opening.
- 10**: A thick, hatched layer surrounding the central cavity, possibly an insulating or structural layer.
- 10a**: A thin layer adjacent to the thick layer 10.
- 2**: A thin layer within the central cavity.
- 54**: A thin layer on the inner surface of the thick layer 10.
- 54a**: A thin layer on the outer surface of the thick layer 10.
- 54b**: A thin layer on the top surface of the thick layer 10.
- 55**: A thin layer on the top surface of the thick layer 10.
- 55a**: A thin layer on the bottom surface of the thick layer 10.
- 60a**: A thin layer on the top surface of the thick layer 10.
- 60b**: A thin layer on the bottom surface of the thick layer 10.
- 70**: A thin layer on the top surface of the thick layer 10.
- 70a**: A thin layer on the bottom surface of the thick layer 10.
- 70b**: A thin layer on the top surface of the thick layer 10.
- 9a**: A thin layer on the bottom surface of the thick layer 10.
- 9c**: A thin layer on the top surface of the thick layer 10.

Arrows indicate the direction of flow or movement within the assembly. A dashed line indicates a hidden internal feature.





FIG.18 PRIOR ART

